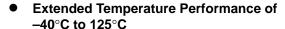
D 8-PIN PACKAGE (TOP VIEW)

SGLS164 - APRIL 2003



- Optimized for Off-line and DC to DC Converters
- Low Start Up Current (<0.5 mA)
- Trimmed Oscillator Discharge Current
- Automatic Feed Forward Compensation
- Pulse-by-Pulse Current Limiting
- Enhanced Load Response Characteristics
- Under-Voltage Lockout With Hysteresis
- Double Pulse Suppression
- High Current Totem Pole Output
- Internally Trimmed Bandgap Reference
- 500 kHz Operation
- Low R_O Error Amp

COMP 8 V_{REF} 0 Vcc V_{FB} 6 OUTPUT ISENSE 3 R_T/C_T 5 **GND D 14-PIN PACKAGE** (TOP VIEW) СОМР П 14 🛮 V_{REF} NC [13 NC 2 12 VCC V_{FB} **∐** 3 NC 4 11 V_C 10 OUTPUT I_{SENSE} [] 5 9 GND NC [] 6 R_T/C_T 7 8 PWR GND

description

The UC2842A/3A/4A/5A family of control ICs is a pin for pin compatible improved version of the UC2842/3/4/5 family. Providing the necessary features to control current mode switched mode power supplies, this family has the following improved features. Start up current is guaranteed to be less than 0.5 mA. Oscillator discharge is trimmed to 8.3 mA. During under voltage lockout, the output stage can sink at least 10 mA at less than 1.2 V for V_{CC} over 5 V

The difference between members of this family are shown in the table below.

| PART NUMBER | UVLO ON | UVLO OFF | MAXIMUM DUTY CYCLE |
|-------------|---------|----------|--------------------|
| UC2842A | 16 V | 10 V | <100% |
| UC2843A | 8.5 V | 7.9 V | <100% |
| UC2844A | 16 V | 10 V | <50% |
| UC2845A | 8.5 V | 7.9 V | <50% |



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

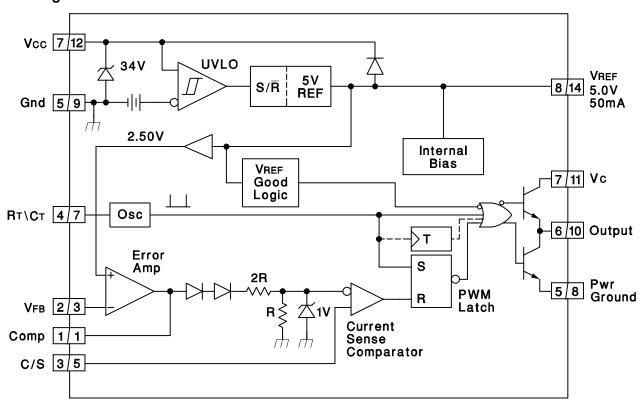


ORDERING INFORMATION[†]

| TA | PACKAGE [‡] | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|----------------------|---------------|--------------------------|---------------------|
| | SOIC-8 – D8 | Tape and reel | UC2842AQD8R | 2842AQ |
| | SOIC-8 - D8 | Tube | UC2842AQD8 | 2842AQ |
| | SOIC-14 – D | Tape and reel | UC2842AQDR | 2842AQ |
| | SOIC-14 – D | Tube | UC2842AQD | 2842AQ |
| | SOIC-8 – D8 | Tape and reel | UC2843AQD8R | 2843AQ |
| | SOIC-8 - D8 | Tube | UC2843AQD8 | 2843AQ |
| | SOIC-14 - D | Tape and reel | UC2843AQDR | 2843AQ |
| –40°C to 125°C | SOIC-14 - D | Tube | UC2843AQD | 2843AQ |
| -40 C to 125 C | SOIC-8 - D8 | Tape and reel | UC2844AQD8R | 2844AQ |
| | SOIC-8 - D8 | Tube | UC2844AQD8 | 2844AQ |
| | SOIC-14 – D | Tape and reel | UC2844AQDR | 2844AQ |
| | SOIC-14 - D | Tube | UC2844AQD | 2844AQ |
| | SOIC-8 - D8 | Tape and reel | UC2845AQD8R | 2845AQ |
| | SOIC-8 - D8 | Tube | UC2845AQD8 | 2845AQ |
| | SOIC-14 – D | Tape and reel | UC2845AQDR | 2845AQ |
| | SOIC-14 – D | Tube | UC2845AQD | 2845AQ |

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

block diagram

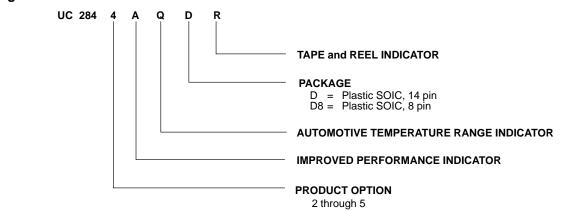


NOTES: 1. A = DIL-8 Pin Number. B = SO-14 Pin Number.

2. Toggle flip flop used only in 2844A and 2845A.

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Ordering Information



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NOTE 1: Long term high–temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

electrical characteristics, T_A = -40°C to 125°C, V_{CC} = 15 V (see Note 1), R_T = 10 $k\Omega$, C_T = 3.3 nF, and T_A = T_J (unless otherwise stated)

| PARAMETER | | TEST CONDITIO | MIN | TYP | MAX | UNITS | |
|--------------------------------|----------------------------------|-----------------------|-----------------------------|------|------|-------|-------|
| Reference Section | | | | | | | |
| Output voltage | T _J = 25°C, | I _O = 1 mA | | 4.95 | 5.0 | 5.05 | V |
| Line regulation voltage | V _{IN} = 12 V to 25 | V | | | 6 | 20 | mV |
| Load regulation voltage | I _O = 1 mA to 20 r | mA | | | 6 | 25 | mV |
| Temperature stability | See Notes 2 and | 3 | | | 0.2 | 0.4 | mV/°C |
| Total output variation voltage | Line, Load, Temp | | | 4.9 | | 5.1 | V |
| Output noise voltage | f = 10 Hz to 10 kl See Note 2 | Hz, | T _J = 25°C | | 50 | | μV |
| Long term stability | 1000 hours, | See Note 2 | T _A = 125°C | | 5 | 25 | mV |
| Output short-circuit current | | | • | -30 | -100 | -180 | mA |
| Oscillator Section | | | | | | | |
| Initial accuracy | See Note 4 | | T _J = 25°C | 47 | 52 | 57 | kHz |
| Voltage stability | V _{CC} = 12 V to 25 | 5 V | | | 0.2 | 1 | % |
| Temperature stability | $T_A = MIN \text{ to } MAX$ | K, See Note 2 | | | 5 | | % |
| Amplitude peak-to-peak | V pin 7, | See Note 2 | | | 1.7 | | V |
| B'ack and a second | V = 1 - 2 - 2 V | On a Nation 5 | T _J = 25°C | 7.8 | 8.3 | 8.8 | |
| Discharge current | V pin 7 = 2 V, | See Note 5 | T _J = Full range | 7.5 | | 8.8 | mA |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[‡]Unless otherwise indicated, voltages are reference to ground and currents are positive into and negative out of the specified terminals.

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electrical characteristics, T_A = -40° C to 125°C, V_{CC} = 15 V (see Note 1), R_T = 10 k Ω , C_T = 3.3 nF, and T_A = T_J (unless otherwise stated)

| PARAMETER | | TEST CONDITIONS | | | | MAX | UNITS |
|--|-----------------------------|---|-----------------------|------|------|------|-------|
| Error Amplifier Section | • | | | • | | | • |
| Input voltage | COMP = 2.5 V | | | 2.45 | 2.5 | 2.55 | V |
| Input bias current | | | | | -0.3 | -1 | μА |
| Open loop voltage gain (A _{VOL}) | V _O = 2 V to 4 V | , | | 65 | 90 | | dB |
| Unity gain bandwidth | See Note 2 | | T _J = 25°C | 0.7 | 1 | | MHz |
| PSRR | V _{CC} = 12 V to 2 | 25 V | • | 60 | 70 | | dB |
| Output sink current | FB = 2.7 V, | COMP = 1.1 V | | 2 | 6 | | mA |
| Output source current | FB = 2.3 V, | COMP = 5 V | | -0.5 | -0.8 | | mA |
| V _{OUT} high | FB = 2.3 V, | $R_L = 15 \text{ k}\Omega \text{ to } \Omega$ | GND | 5 | 6 | | V |
| VOUT low | FB = 2.7 V, | $R_L = 15 \text{ k}\Omega \text{ to } $ | /REF | | 0.7 | 1.1 | V |
| Current Sense Section | • | | | • | | | |
| Gain | See Notes 6 an | d 7 | | 2.85 | 3 | 3.15 | V/V |
| Maximum input signal | COMP = 5 V, | See Note 6 | | 0.9 | 1 | 1.1 | V |
| PSRR | V _{CC} = 12 V to 2 | 25 V, See Note 6 | | | 70 | | dB |
| Input bias current | | | | | -2 | -10 | μΑ |
| Delay to output | I _{SENSE} = 0 V t | o 2 V, See I | Note 2 | | 150 | 300 | ns |
| Output Section (OUT) | | | | | | | |
| | I _{OUT} = 20 mA | | | | 0.1 | 0.4 | |
| Low-level output voltage | I _{OUT} = 200 mA | 1 | | | 15 | 2.2 | V |
| | I _{OUT} = -20 mA | 1 | | 13 | 13.5 | | |
| High-level output voltage | I _{OUT} = -200 m | A | | 12 | 13.5 | | V |
| Rise time | C _L = 1 nF, | See Note 2 | T _J = 25°C | | 50 | 150 | ns |
| Fall time | C _L = 1 nF, | See Note 2 | T _J = 25°C | | 50 | 150 | ns |
| UVLO saturation | V _{CC} = 5 V, | I _{OUT} = 10 mA | <u> </u> | | 0.7 | 1.2 | V |
| Undervoltage Lockout Section | 1 00 | | | | | | |
| | | | UC2842A, UC2844A | 15 | 16 | 17 | |
| Start threshold | | | UC2843A, UC2845A | 7.8 | 8.4 | 9 | V |
| | | | UC2842A, UC2844A | 9 | 10 | 11 | ., |
| Minimum operation voltage after turn on | | | UC2843A, UC2845A | 7 | 7.6 | 8.2 | V |

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electrical characteristics, T_A = -40° C to 125°C, V_{CC} = 15 V (see Note 1), R_T = 10 k Ω , C_T = 3.3 nF, and T_A = T_J (unless otherwise stated)

| PARAMETER | | TEST CONDITIONS | | | | | UNITS |
|--|-------------------------|-----------------|------------------|----|-----|-----|-------|
| PWM Section | · | | | | | | |
| Manifestor delta socia | | | UC2842A, UC2843A | 94 | 96 | 100 | 0, |
| Maximum duty cycle | | | UC2844A, UC2845A | 47 | 48 | 50 | % |
| Minimum duty cycle | | | | | | 0 | % |
| Total Standby Current | | | | | | | |
| Start-up current | | | | | 0.3 | 0.5 | mA |
| Operating supply current | FB = 0 V, | SENSE = 0 V | | | 11 | 17 | mA |
| V _{CC} internal zener voltage | I _{CC} = 25 mA | | | 30 | 34 | | V |

NOTES: 1. Adjust V_{CC} above the start threshold before setting at 15 V.

- 2. Not production tested.
- 3. Temperature stability, sometimes referred to as average temperature coefficient, is described by the equation:

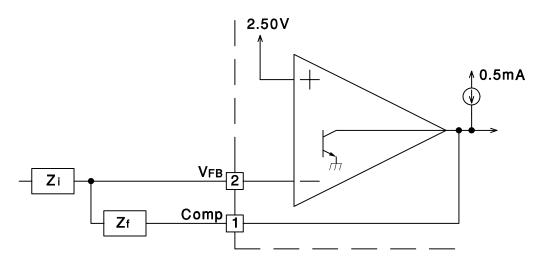
Temp Stability =
$$\frac{V_{REF} (max) - V_{REF} (min)}{T_{J} (max) - T_{J} (min)}$$
. $V_{REF} (max)$ and $V_{REF} (min)$ are the maximum and minimum reference voltage measured

over the appropriate temperature range. Note that the extremes in voltage do not necessarily occur at the extremes in temperature.

- 4. Output frequency equals oscillator frequency for the UC2842A and UC2843A. Output frequency is one half oscillator frequency for the UC2844A and UC2845A.
- 5. This parameter is measured with $R_T = 10 \text{ k}\Omega$ to V_{REF} . This contributes approximately 300 μA of current to the measurement. The total current flowing into the $R_{T/C}$ pin will be approximately 300 μA higher than the measured value.
- 6. Parameter measured at trip point of latch with VFB at 0 V.
- 7. Gain is defined by: $A = \frac{\Delta V_{COMP}}{\Delta V_{SENSE}}; 0 \le V_{SENSE} \le 0.8 \text{ V}.$

•PA

RAMETER MEASUREMENT INFORMATION



Error Amp can source and sink up to 0.5 mA, and sink up to 2 mA.

Figure 1. Error Amp Configuration



PARAMETER MEASUREMENT INFORMATION

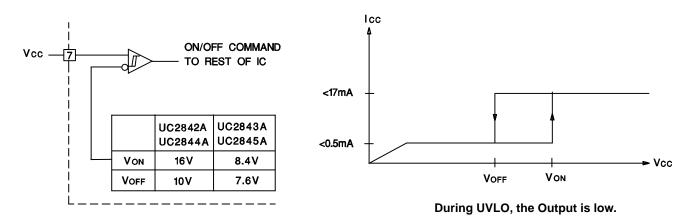
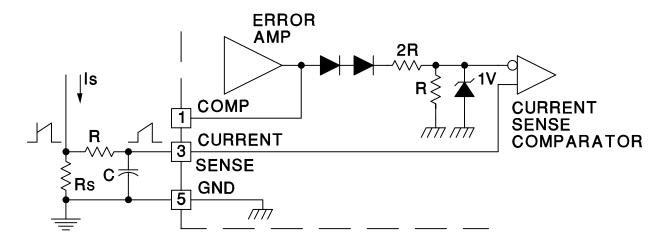


Figure 2. Under Voltage Lockout



Peak Current (Is) is Determined By The Formula:

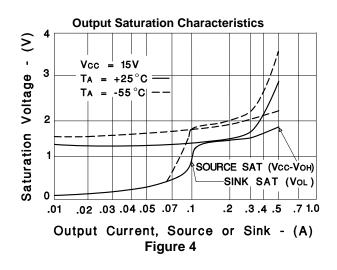
$$Ismax'\frac{1.0V}{RS}$$

A small RC filter may be required to supress switch transients.

Figure 3. Current Sense Circuit

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PARAMETER MEASUREMENT INFORMATION



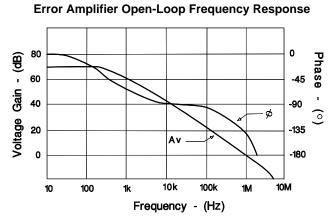


Figure 5

PLICATION INFORMATION

Oscillator Frequency vs Timing Resistance

RT (ohms) RT (Ohms)

Maximum Duty Cycle vs Timing Resistor

AP

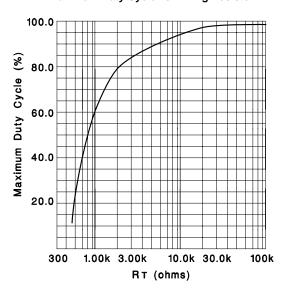
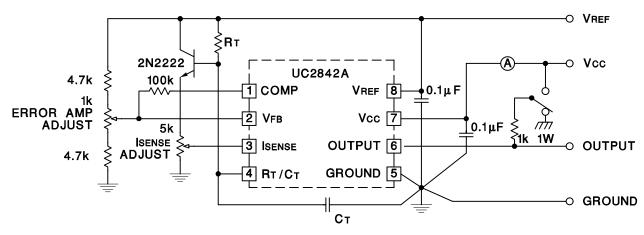


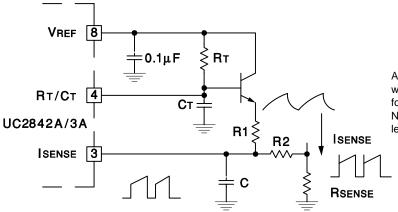
Figure 6. Oscillator

APPLICATION INFORMATION



High peak currents associated with capacitive loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to pin 5 in a single point ground. The transistor and 5k potentiometer are used to sample the oscillator waveform and apply an adjustable ramp to pin 3.

Figure 7. Open-Loop Laboratory Text Fixture



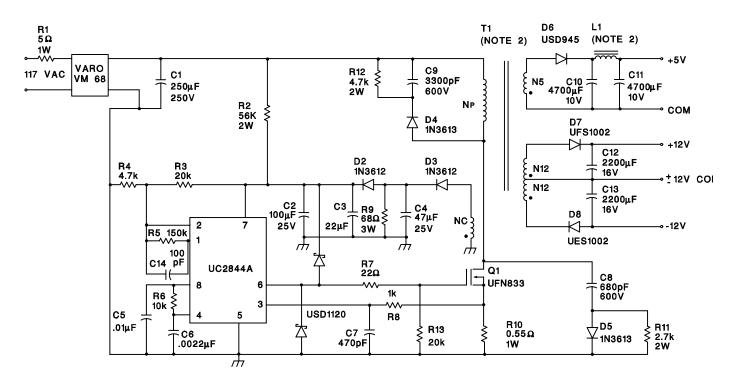
A fraction of the oscillator ramp can be resistively summed with the current sense signal to provide slope compensation for converters requiring duty cycles over 50%.

Note that capacitor, C, forms a filter with R2 to suppress the leading edge switch spikes.

Figure 8. Slope Complression

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APPLICATION INFORMATION



Power Supply Specifications

1. Input Voltage 95VAC to 130VAC (50Hz/60Hz)

Line Isolation 3750V
 Switching Frequency 40 kHz
 Efficiency, Full Load 70%

5. Output Voltage:

A. +5V, ±5%; 1A to 4A Load

B. \pm 12V, \pm 3%; 0.1A to 0.3A Load Ripple voltage: 100 mV P-P Max C. \pm 12V, \pm 3%; 0.1A to 0.3A Load Ripple voltage: 100 mV P-P Max

Figure 9. Off-Line Flyback Regulator

17-Aug-2012

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|------------|--------------|--------------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| UC2842AQD | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | |
| UC2842AQD8 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2842AQD8R | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2842AQDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2843AQD | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2843AQD8 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2843AQD8G4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2843AQD8R | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2843AQD8RG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2843AQDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2845AQD | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2845AQD8 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2845AQD8R | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| UC2845AQDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

17-Aug-2012

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

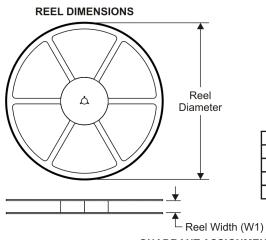
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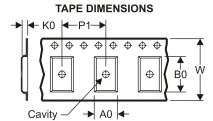
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PACKAGE MATERIALS INFORMATION

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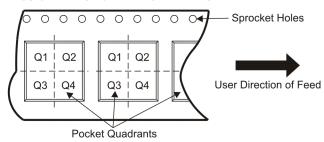
TAPE AND REEL INFORMATION





| _ | | |
|---|----|---|
| | A0 | Dimension designed to accommodate the component width |
| Γ | B0 | Dimension designed to accommodate the component length |
| | | Dimension designed to accommodate the component thickness |
| | W | Overall width of the carrier tape |
| Γ | P1 | Pitch between successive cavity centers |

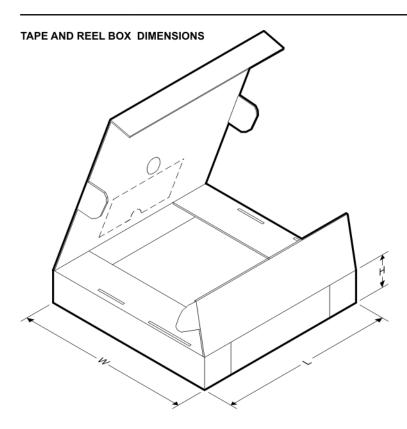
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter | | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|-----------------|--------------------|---|------|------------------|------------------------|------------|------------|------------|------------|-----------|------------------|
| UC2842AQD8R | SOIC | D | 8 | 2500 | (mm) 330.0 | W1 (mm) 12.4 | 6.4 | 5.2 | 2.1 | 4.0 | 12.0 | Q1 |
| UC2843AQD8R | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 4.0 | 12.0 | Q1 |
| UC2845AQD8R | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 4.0 | 12.0 | Q1 |

www.ti.com 9-Dec-2010



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| UC2842AQD8R | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| UC2843AQD8R | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| UC2845AQD8R | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



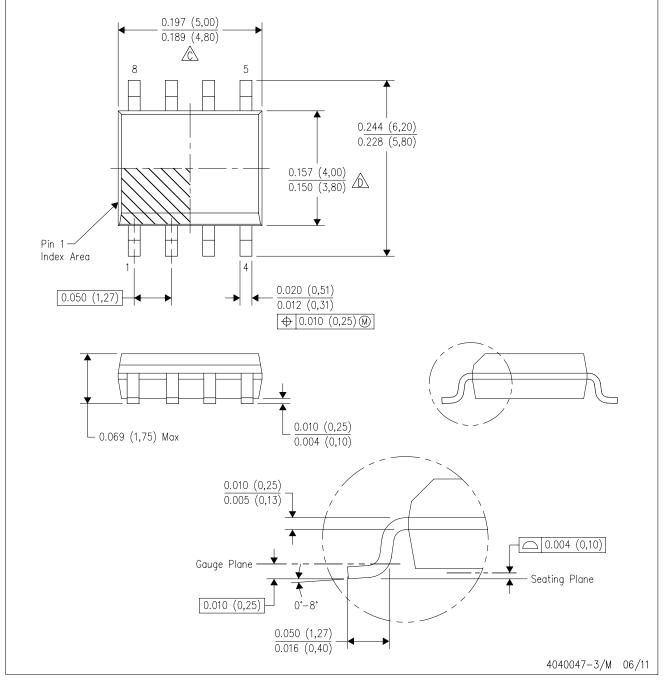
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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